

### ***N channel 100V MOSFET***

#### 1. Description

The HS15N10DA is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and low in-line power loss that are needed in a very small outline surface mount package.

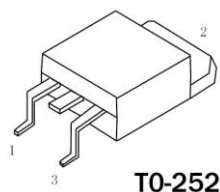
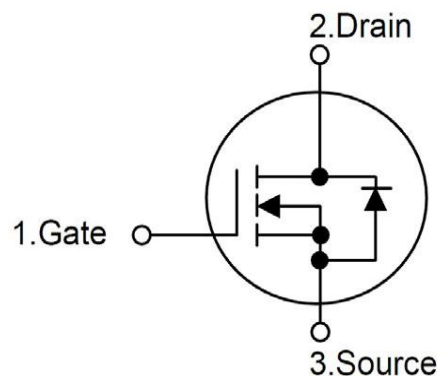
#### 2. Feature

- $R_{DS(ON)} \leq 100m\Omega @ V_{GS}=10V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current

V <sub>DS</sub>	100	V
R <sub>DS(on)</sub>	100	mΩ
I <sub>D</sub>	15	A

#### 3. Pin configuration

Order Number	Package
HS15N10DA	T0-252



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**4. Absolute maximum ratings (Tc=25°C Unless Otherwise Noted)**

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V <sub>DSS</sub>	100	V
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current	T <sub>c</sub> =25°C	I <sub>D</sub>	15	A
	T <sub>c</sub> =70°C		14	A
Pulsed Drain Currenta		I <sub>DM</sub>	59	A
Power Dissipation	T <sub>c</sub> =25°C	PD	34.7	W
	T <sub>c</sub> =70°C		22.2	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

**5. Thermal characteristics**

Parameter	Symbol	Ratings	Units
Thermal resistance, case to sink typ.	R <sub>thCS</sub>	0.5	°C/W
Thermal resistance junction to case.	R <sub>thJC</sub>	3.6	°C/W
Thermal resistance junction to ambient.	R <sub>thJA</sub>	110	°C/W

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**6. Electrical characteristics (TA =25°C Unless Otherwise Specified)**

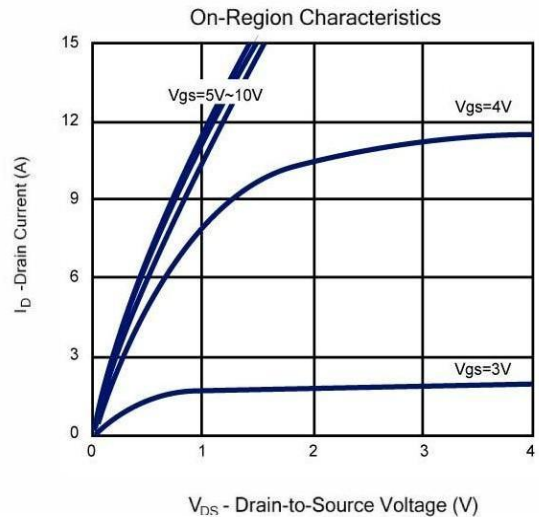
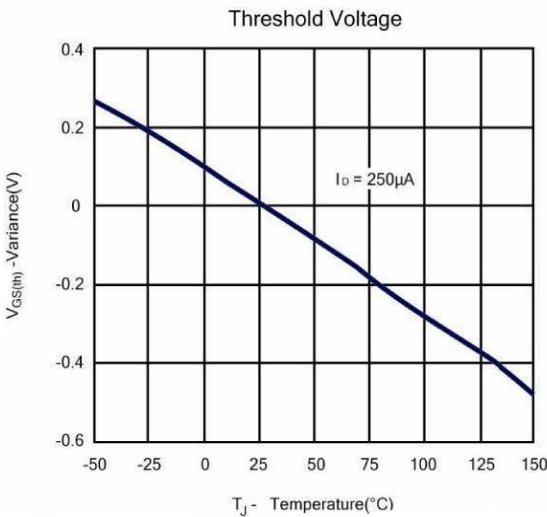
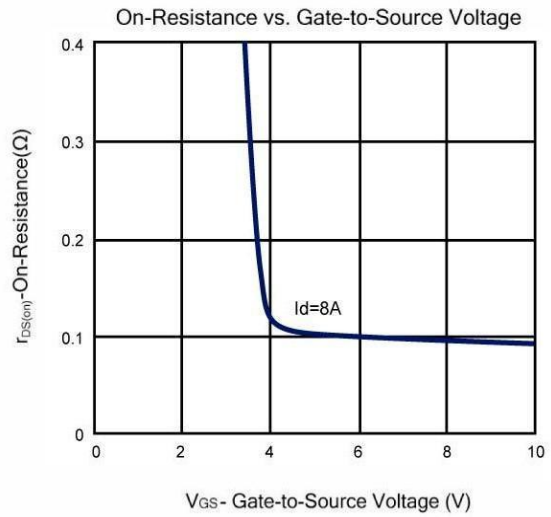
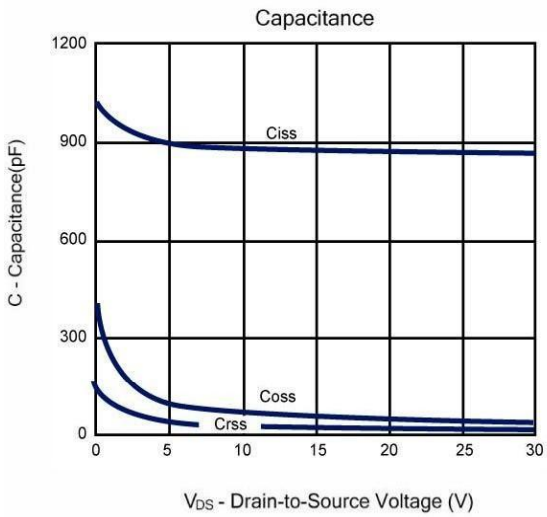
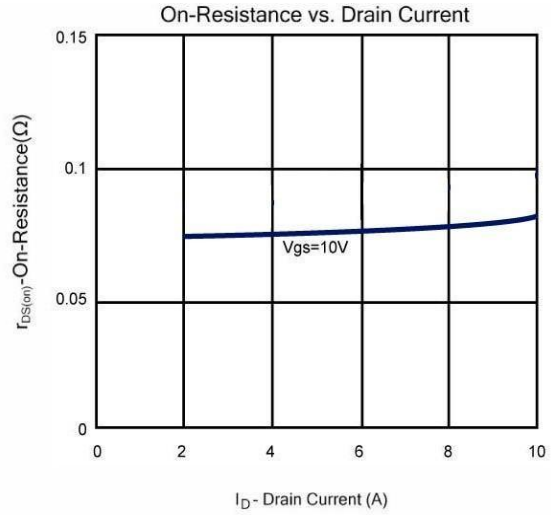
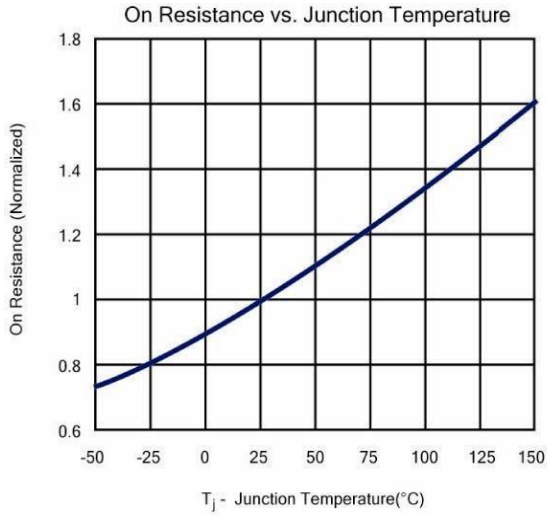
Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250μA	100	-	-	V
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1	-	3	V
IGSS	Gate-Body Leakage	VDS=0V, VGS=±20V	-	-	±100	μA
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V	-	-	1	μA
RDS(ON)	Drain-Source On-Resistance	VGS=10V, ID=8A	-	80	100	mΩ
VSD	Diode Forward Voltage	IS=8A, VGS=0V	-	0.9	1.2	V
<b>DYNAMIC</b>						
Qg	Total Gate Charge	VDD=80V, VGS=10V, ID=10A	-	13	-	nC
Qgs	Gate-Source Charge		-	4.6	-	
Qgd	Gate-Drain Charge		-	7.6	-	
Ciss	Input Capacitance	VDS=15V, VGS=0V, f=1MHz	-	890	-	pF
Coss	Output Capacitance		-	58	-	
Crss	Reverse Transfer Capacitance		-	23	-	
td(on)	Turn-On Delay Time	VDS=50V, RG=1Ω, RL=5Ω, VGEN=10V	-	14	-	ns
tr	Turn-On Rise Time		-	33	-	
td(off)	Turn-Off Delay Time		-	39	-	
tf	Turn-Off Fall Time		-	5	-	
ISD	Continuous drain-source current		-	-	15	A
ISM	Pulsed drain-source current		-	-	59	A

Notes :a. pulse test:pulse width 300 us,duty cycle 2% ,Guaranteed by design,not subject to production testing.

b. HOMSEMI reserves the right to improve product design,functions and reliability without notice.

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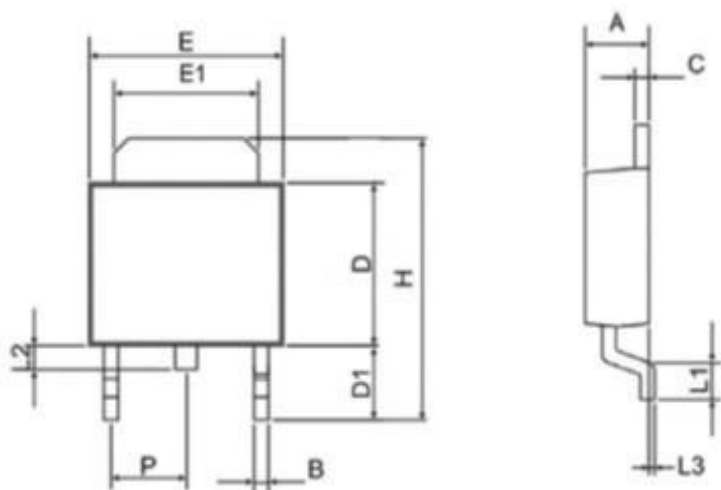
#### 7. Typical Characteristics (T<sub>J</sub> = 25°C Noted)



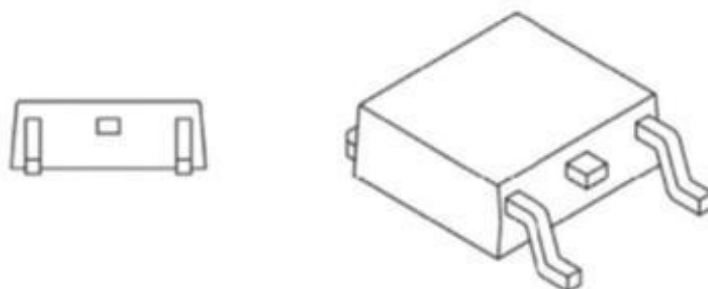
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**8.Package Information:**

**Unit: mm**



SYMBOL	MIN	MAX
A	2.1	2.5
B	0.4	0.9
C	0.4	0.9
D	5.3	6.3
D1	2.2	2.9
E	6.3	6.75
E1	4.8	5.5
L1	0.9	1.8
L2	0.5	1.1
L3	0	0.2
H	8.9	10.4
P	2.30 BSC	



**TO-252**